



# Radiation tolerance study using 8-inch full-wafer silicon sensors for CMS HGICAL

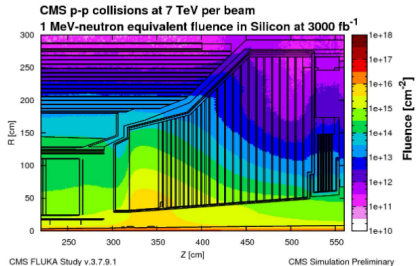
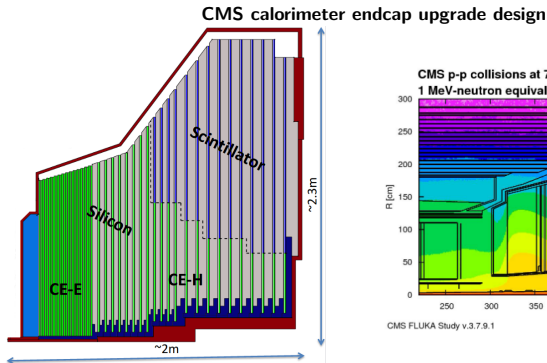
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on behalf of the CMS HGICAL Silicon Group at CERN

The 39th RD50 Workshop  
Valencia, Spain  
November 19, 2021

# Upgrade for High - Luminosity LHC



- ▶ Increase in luminosity and radiation level at HL-LC
- ▶ CMS detector needs upgrade before the HL-LHC
- ▶ One of the upgrades is the replacement of the Endcap Calorimeter by a High Granularity Calorimeter (HGCal)
- ▶ HGCal will be based on silicon sensors in high radiation regions

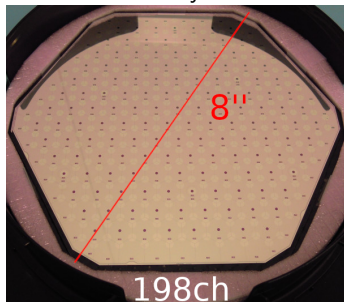


# Silicon Sensors for CMS HGCAL

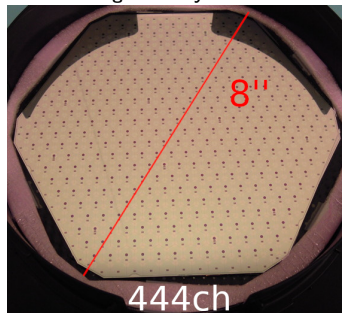


- ▶ Silicon pad sensors will cover a total area of  $620 \text{ m}^2$
- ▶ Hexagonal shape for optimization of wafer usage
- ▶ Three different thicknesses adapted to radiation fluences
- ▶ Two geometries: Low-Density (LD) and High-Density (HD)
- ▶ Each sensor segmented into several hundred cells of hexagonal shape of  $0.5$  to  $1.1 \text{ cm}^2$  in size
- ▶ Prototypes sensors (56 LD, 32 HD) have been delivered in Summer 2020 and partially sent to RINSC

Low-Density sensor



High-Density sensor

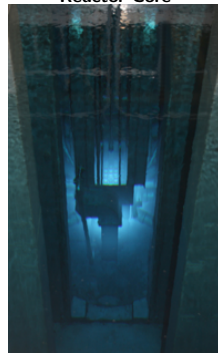


# New irradiation facility: RINSC

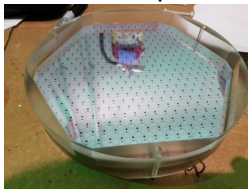


- ▶ Rhode Island Nuclear Science Centre, US
- ▶ Neutron irradiation of the sensors up to  $10^{16}$  1MeV  $n_{eq}/\text{cm}^2$  in 180 min
- ▶ Four sensors in a puck irradiated at a time
- ▶ Irradiation of the 8-inch wafers possible only at RINSC because of the beamport width

Reactor Core



Sensor in a puck



Cylinder



Beamport



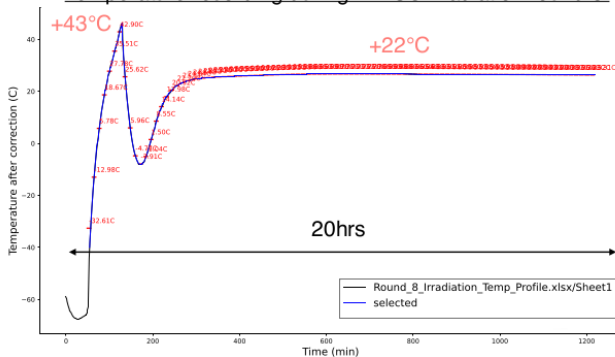
▶ [RINSC webpage](#)

# Specifics of RINSC irradiation facility



- ▶ High temperatures during irradiation
- ▶ Temperature during the irradiation was recorded
- ▶ Annealing already during irradiation and after
- ▶ Additional annealing up to 80min at 60°C done at CERN

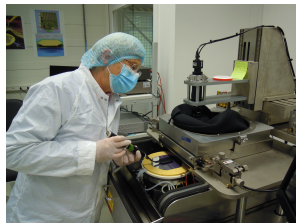
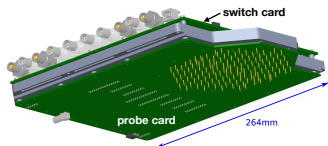
Temperature recording during RINSC irradiation round 8:



Target fluence:  $5 \cdot 10^{15}$  1MeV  $n_{eq}/cm^2$ , irradiation time: 76 min

## The probe station

- ▶ Use custom-made “ARRAY system” - full wafer IV+CV probe card
- ▶ Simultaneously contact and bias all pads in a sensor
- ▶ Per-cell IV and CV of all cells before and after additional annealing
- ▶ Temperature controlled chuck, enables measurements at  $-40^{\circ}\text{C}$
- ▶ Temperature stable with time, less than  $1^{\circ}\text{C}$  inhomogeneity across the chuck at  $-40^{\circ}\text{C}$



# Irradiation of HGCAL silicon sensor prototypes



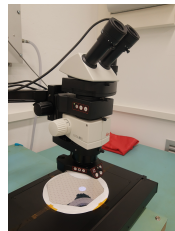
- ▶ Started in August 2020, finished in June 2021
- ▶ 26 sensors characterised at CERN
- ▶ 7 irradiation rounds
- ▶ 5 different target fluences



# Visual inspection is important

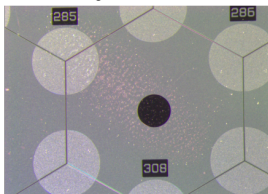


- ▶ Identification of mechanical defects
- ▶ Removal of dust
  - ▶ Particular focus on guard ring (GR) area
- ▶ Fully manual inspection
  - ▶ Now partially automated; working on full automation with the use of ML



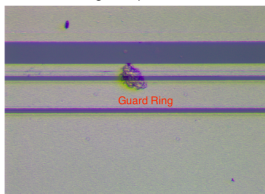
## Examples of features observed on irradiated sensors:

e.g. water residual

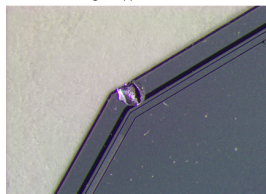


Harmless

e.g. dust particles



e.g. chipped corners



Dangerous

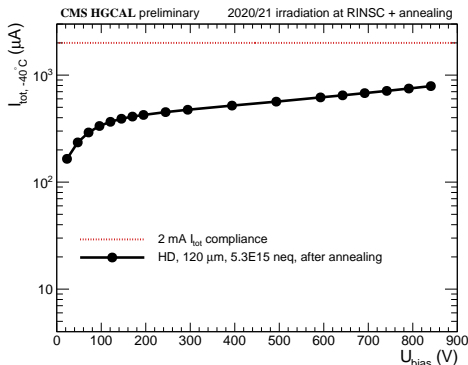




# IV test measurement at $-40^{\circ}\text{C}$



- ▶ Measure total leakage current by increasing bias voltage by 10V up to 850V or  $I_{tot}=2\text{mA}$
- ▶ 2mA is a system-defined compliance limit to protect the ARRAY test system
- ▶ Total leakage current well below 2mA for most sensors
- ▶ Note log scale



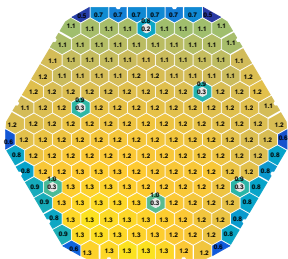
# IV measurement at $-40^{\circ}\text{C}$



- ▶ Additional annealing lowers leakage current
- ▶ Assume leakage current as proxy for fluence
- ▶ Fluence profile visible

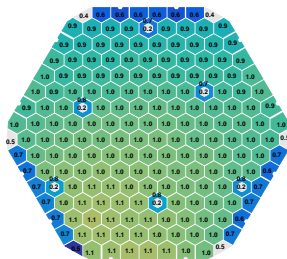
## Per-pad leakage current before and after additional annealing

LD, 300  $\mu\text{m}$ ,  $0.9\text{E}15 \text{ neq}/\text{cm}^2$



Values for  $U = 600.0 \text{ V}$

LD, 300  $\mu\text{m}$ ,  $0.9\text{E}15 \text{ neq}/\text{cm}^2$

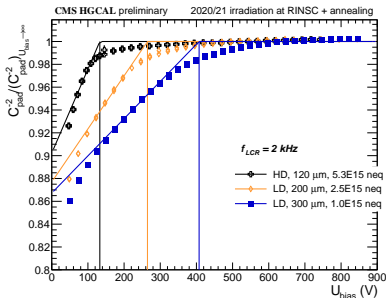
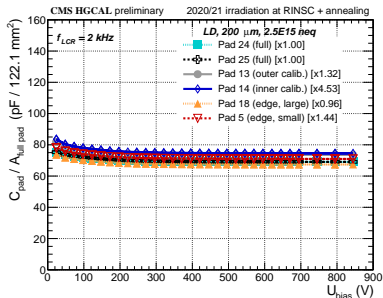


Values for  $U = 600.0 \text{ V}$

# Capacitance and depletion voltage



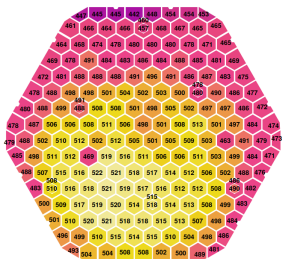
- ▶ Capacitance of partial cells normalized to the full-cell area
- ▶ Obtained values in agreement within  $\pm 5\%$
- ▶ Depletion voltage estimation based on squared-inverse of open-corrected serial capacitance
- ▶ Thicker sensors show higher depletion voltage at the same fluence



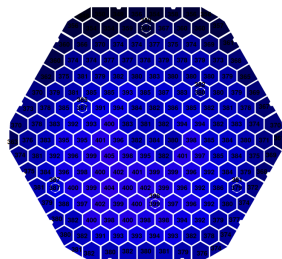
- ▶ Additional annealing lowers the depletion voltage

## Per-pad depletion voltage estimation before and after additional annealing

LD, 300  $\mu\text{m}$ ,  $0.9\text{E}15$  neq/ $\text{cm}^2$



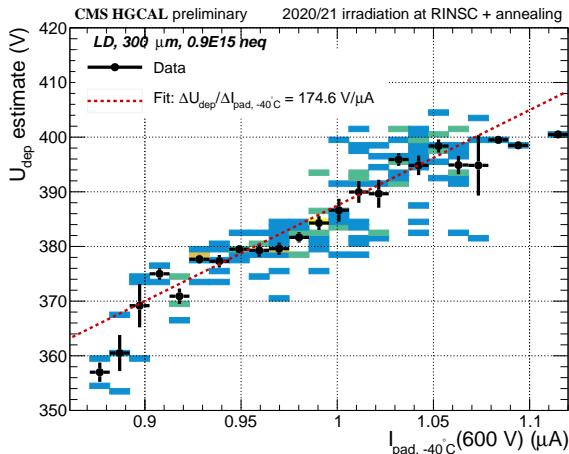
LD, 300  $\mu\text{m}$ ,  $0.9\text{E}15$  neq/ $\text{cm}^2$



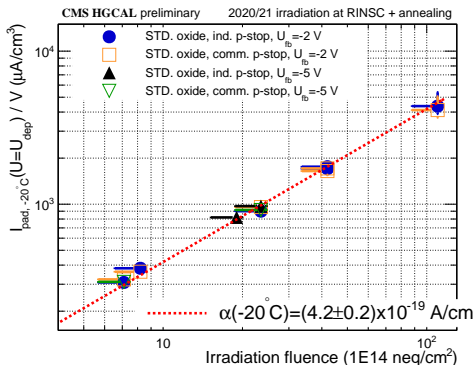
# Correlation between fluence and depletion voltage



- Higher depletion voltage observed for higher leakage current (proxy for fluence)



# Current related damage rate



$$\frac{I}{V} = \alpha \cdot \phi$$

- ▶ Systematic uncertainties: up to 20% for fluence and 7% for leakage current
- ▶  $\alpha_{-20^\circ\text{C}} = (4.2 \pm 0.2 - 0.8 + 0.2) \times 10^{-19}$  A/cm for current at  $U_{\text{dep}}$
- ▶  $\alpha_{-20^\circ\text{C}} = (5.9 \pm 0.2 - 1.1 + 0.3) \times 10^{-19}$  A/cm for current at 600V
- ▶  $\alpha_{-20^\circ\text{C}} = (6.9 \pm 0.3 - 1.4 + 0.4) \times 10^{-19}$  A/cm for current at 800V



- ▶ One of the upgrades in CMS experiment is the replacement of current endcap calorimeters with the High Granularity Calorimeter.
- ▶ Silicon sensor will cover an area of over  $600\text{m}^2$  in HGCAL
- ▶ 8-inch prototype silicon wafers were irradiated at RINSC and electrically characterised at CERN for the first time.
- ▶ Additional annealing reduces leakage current and depletion voltage
- ▶ Depletion voltage and leakage current (as proxy for the fluence) positively correlated
- ▶ Preliminary alpha-value (after annealing):  
 $\alpha_{-20^\circ\text{C}} = (4.2 \pm 0.2 - 0.8 + 0.2) \times 10^{-19} \text{ A/cm}$

## List of the sensors characterised at CERN

Round	ID	Temp [°C]	P-stop	Thickness [µm]	Geometry	Flat band voltage [V]	P-Stop conc.	Oxide quality	Material	Target tulence [neg/cm2]	RINSC Irradiation
1	1004	-30 & -40	ind.	300	LD	-5	STD	STD	FZ	6.5E+14	26 Aug 2020
	1002					-2					
	1101					-5					
	1102					-2					
3	3002	-40	ind.	120	HD	-2	0.5*STD	STD	epi	1.0E+16	20 Oct 2020
	3102		com.								
	3003		ind.								
	3103		com.								
4	2109	-40	com.	200	LD	-5	STD	Type B	FZ	2.5E+15	21 Jan 2021
	2110							Type C			
	2111							Type D			
	2112							Type E			
5	2004	-40	ind.	200	LD	-5	STD	STD	FZ	2.5E+15	28 Jan 2021
	2002		-2								
	2105		-5								
	2114		-2								
8	3009	-40	ind.	120	HD	-2	STD	STD	epi	5.0E+15	11 Mar 2021
	3010		com.								
	3109										
	3110										
10	1013	-40		ind.	300	LD	-2	STD	STD	FZ	1.0E+15
	1114		com.								
	N0538 WNo.3		ind.								
	N0538 WNo.25		com.								
11	N0541 WNo.4	-40	ind.	200	LD	-5	STD	STD	FZ	2.5E+15	6 May 2021
	N0538 WNo.10					-2					
						Type C					

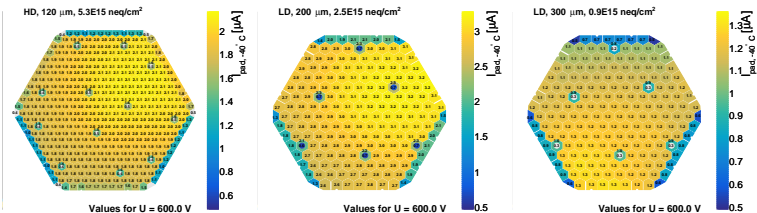


# Backup

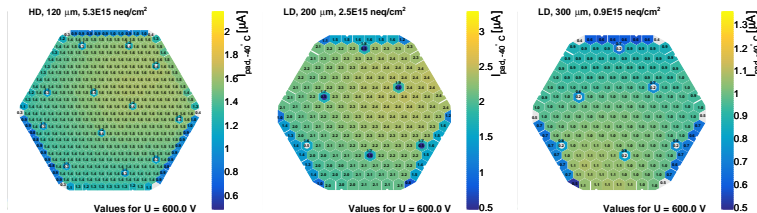
## IV measurements at $-40^{\circ}\text{C}$



### Per-pad leakage current before additional annealing



### Per-pad leakage current after additional annealing

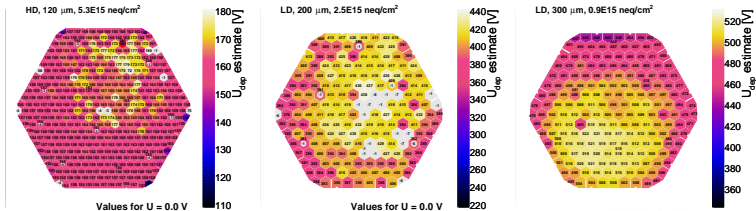


# Backup

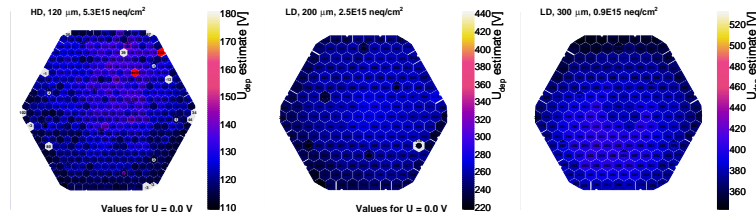
## CV measurements at $-40^{\circ}\text{C}$

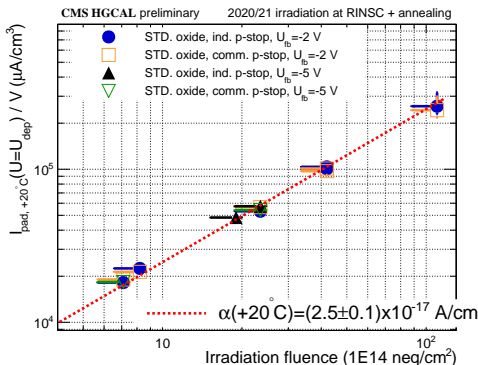


### Per-pad depletion voltage estimation before additional annealing



### Per-pad depletion voltage estimation after additional annealing





- ▶ Systematic uncertainties: up to 20% for fluence and 7% for leakage current
- ▶  $\alpha_{20^\circ\text{C}} = (2.5 \pm 0.1 - 0.5 + 0.1) \times 10^{-17} \text{ A/cm}$  for current at  $U_{dep}$
- ▶  $\alpha_{20^\circ\text{C}} = (3.5 \pm 0.1 - 0.7 + 0.2) \times 10^{-17} \text{ A/cm}$  for current at 600V
- ▶  $\alpha_{20^\circ\text{C}} = (4.1 \pm 0.2 - 0.8 + 0.2) \times 10^{-17} \text{ A/cm}$  for current at 800V